

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- Ideal for printed circuit board
- Lead tin plated copper
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product

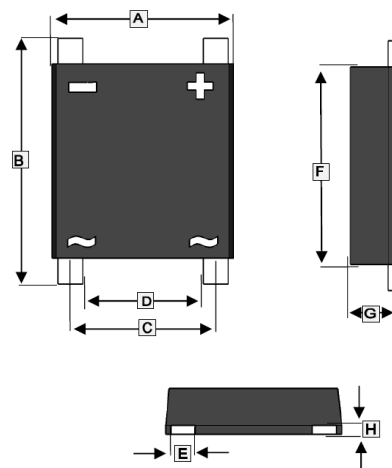
MECHANICAL DATA

- Polarity: Symbol molded on body
- Mounting position :Any

PACKAGE INFORMATION

Package	MPQ	Leader Size
EBS	5K	13 inch

EBS



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.9	5.1	E	0.6	0.7
B	6.0	6.4	F	5.3	5.5
C	3.9	4.1	G	1.15	1.27
D	3.2	3.5	H	0.15	0.25

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter	Symbol	Part Number	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	V
Maximum RMS Bridge Input Voltage	V_{RMS}	140	V
Maximum DC Blocking Voltage	V_{DC}	200	V
Maximum Average Forward Rectified Output	I_F	2	A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	50	A
Maximum Forward Voltage @ 2A	V_F	0.9	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_C=25^{\circ}C$	0.2	mA
	$T_C=100^{\circ}C$	5	
Typical Junction Capacitance ¹	C_J	35	pF
Typical Thermal Resistance ²	$R_{\theta JA}$	100	°C / W
Typical Thermal Resistance ²	$R_{\theta JC}$	50	°C / W
Operating and Storage temperature range	T_J, T_{STG}	-55~150	°C

Note:

1. Measured at 1.0MHZ and applied reverse voltage of 4.0V DC
2. Device mounted on FR 4 substrate, 1" *1" , 2oz, single sided, PC boards with 0.1"* 0.15" copper pad.

RATINGS AND CHARACTERISTIC CURVES

FIG. 1-TYPICAL FORWARD CURRENT DERATING CURVE

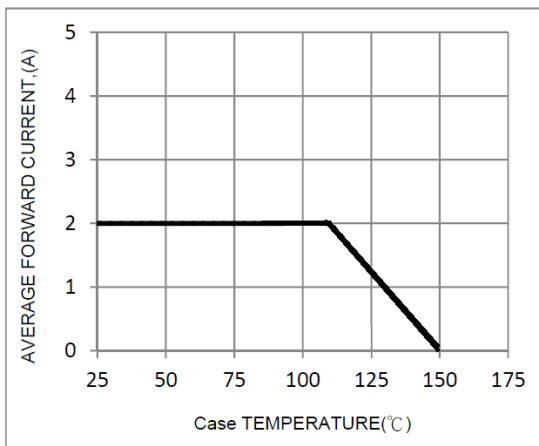


FIG. 2-TYPICAL FORWARD CHARACTERISTICS

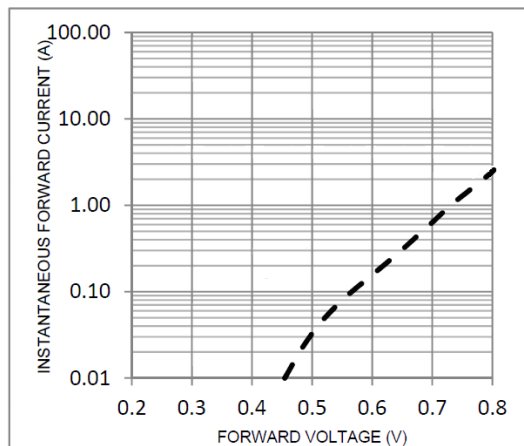


FIG. 3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

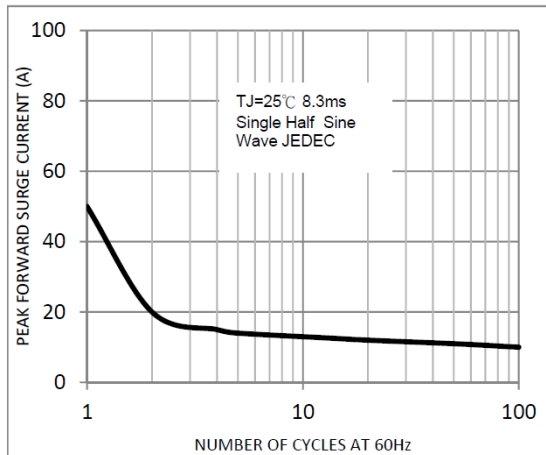


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

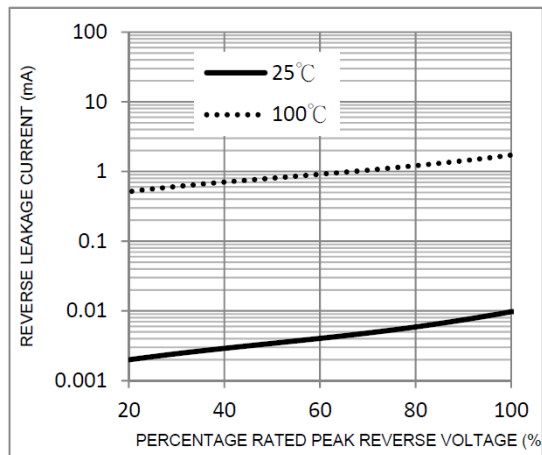


FIG. 5-TYPICAL JUNCTION CAPACITANCE

